

PRODUCT SPECIFICATION

Part No.:	AC-OPAOC-8G800-XX	
Description:	800G OSFP-RHS AOC , MMF 850nm 0.5-100m	
Release Date	Rev.	Revision Change Description
2024/04/30	A0	New Release
2024/09/08	A1	Update the Mechanical drawing
2025/09/04	A2	Version Update

Features

- ✧ Data Rate 106.25 Gb/s PAM4 per lane
- ✧ Digital Diagnostics Monitoring Interface
- ✧ Reach up to 100m over MMF(OM4)
- ✧ Hot-pluggable OSFP form factor
- ✧ 850nm VCSEL laser and PIN receiver
- ✧ Commercial operating case temperature range: 0~ 70°C
- ✧ RoHS-6 compliant
- ✧ TDEC< 4.4dB
- ✧ Single 3.3V Power Supply
- ✧ Power Dissipation< 14W

Application

- ✧ Data center
- ✧ 800G-AOC

Standard

- ✧ IEEE Std 802.3ck
- ✧ 800G OSFP-RHS AOC MSA and CMIS5.1

Specification:

Absolute Maximum Ratings				
Parameter	Symbol	Min	Max	Unit
Storage Ambient Temperature	T _{STG}	-40	85	°C
Operating Humidity	H _o	5	85	%
Power Supply Voltage	V _{cc}	-0.3	3.6	V
Signal Input Voltage		V _{cc} -0.3	V _{cc} +0.3	V

Recommended Operating Conditions					
Parameter	Symbol	Min	Typical	Max	Unit
Operating Case Temperature	T _c	0		70	°C
Power Supply Voltage	V _{cc}	3.13	3.3	3.47	V
Data Rate, each Lane (PAM4)			106.25		Gbps
Fiber Length 50/125μm core MMF		-	-	100	m

Optical transmitter Characteristics						
Parameter	Symbol	Min	Typical	Max	Unit	Notes
Launched Power (avg.) Per Lane	P _{avg}	-4.6		4	dBm	
Wavelength Range	λ ₀	844	850	863	nm	
Spectral Width(-20dB)	Δλ			0.6	nm	
Extinction Ratio	ER	2.5			dB	
Transmitter OFF Output Power	P _{Off}			-30	dBm	
Optical Modulation Amplitude(OMA outer)	OMA	-2.6		3.5	dBm	
Transmitter and dispersion eye closure(TDECQ)	TDECQ			4.4	dB	

Optical receiver Characteristics						
Parameter	Symbol	Min	Typical	Max	Unit	Notes
Receiver Wavelength Range		844	850	863	nm	
Average Receiver Power Per Lane		-6.4		4	dBm	
Receiver Sensitivity (OMA _{outer}) Max(TECQ, TDECQ) ≤ 1.8dB 1.8 < max(TECQ, TDECQ) ≤	P _{Sen}			-4.6 -6.4+TEC Q	dBm	1

4.4dB						
Optical Power Input Overload	P_{in-max}	3.5			dBm	
Receiver Reflectance	R_r			-12	dB	

Notes:

1. BER=2.4E-4; PRBS31Q@53.125GBd.

Pin Definition

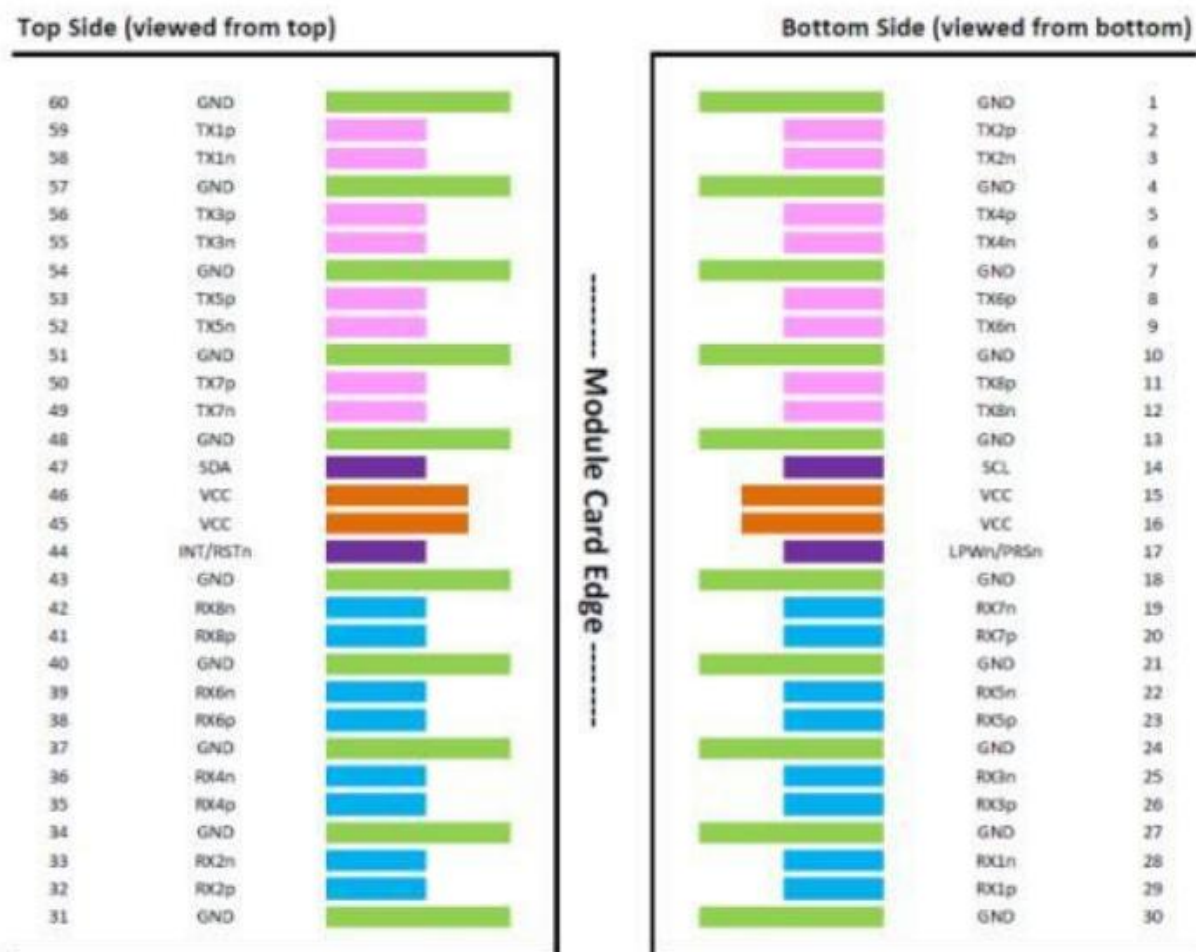


Figure1 OSFP 60-pin connector

Pin	Symbol	Description	Logic	Direction	Plug Sequence	Note
1	GND	Ground			1	
2	TX2p	Transmitter Data Non-Inverted	CML-I	Input from Host	3	
3	TX2n	Transmitter Data Inverted	CML-I	Input from Host	3	
4	GND	Ground			1	
5	TX4p	Transmitter Data Non-Inverted	CML-I	Input from Host	3	
6	TX4n	Transmitter Data Inverted	CML-I	Input from Host	3	
7	GND	Ground			1	
8	TX6p	Underfined	CML-I	Input from Host	3	
9	TX6n	Underfined	CML-I	Input from Host	3	
10	GND	Ground			1	
11	TX8p	Underfined	CML-I	Input from Host	3	
12	TX8n	Underfined	CML-I	Input from Host	3	
13	GND	Ground			1	

14	SCL	2-wire Serial interface clock	LVC MOS- I/O	Bi-directional	3	Open-Drain with pull up resistor on H
15	VCC	+3.3V Power		Power from Host	2	
16	VCC	+3.3V Power		Power from Host	2	
17	LPWn/PRSn	Low-Power Mode / Module Present	Multi-Level	Bi-directional	3	See pin description for required circuit
18	GND	Ground			1	
19	RX7n	Underfined	CML-O	Output to Host	3	
20	RX7p	Underfined	CML-O	Output to Host	3	
21	GND	Ground			1	
22	RX5n	Underfined	CML-O	Output to Host	3	
23	RX5p	Underfined	CML-O	Output to	3	
24	GND	Ground			1	
25	RX3n	Receiver Data Inverted	CML-O	Output to Host	3	
26	RX3p	Receiver Data Non-Inverted	CML-O	Output to Host	3	
27	GND	Ground			1	
28	RX1n	Receiver Data Inverted	CML-O	Output to Host	3	
29	RX1p	Receiver Data Non-Inverted	CML-O	Output to Host	3	
30	GND	Ground			1	
31	GND	Ground			1	
32	RX2p	Receiver Data Non-Inverted	CML-O	Output to Host	3	
33	RX2n	Receiver Data Inverted	CML-O	Output to Host	3	
34	GND	Ground			1	
35	RX4p	Receiver Data Non-Inverted	CML-O	Output to Host	3	
36	RX4n	Receiver Data Inverted	CML-O	Output to Host	3	
37	GND	Ground			1	
38	RX6p	Underfined	CML-O	Output to Host	3	
39	RX6n	Underfined	CML-O	Output to Host	3	
40	GND	Ground			1	
41	RX8p	Underfined	CML-O	Output to Host	3	
42	RX8n	Underfined	CML-O	Output to Host	3	
43	GND	Ground			1	
44	INT/RSTn	Module Interrupt / Module Reset	Multi-Level	Bi-directional	3	See pin description for required circuit
45	VCC	+3.3V Power		Power from Host	2	
46	VCC	+3.3V Power		Power from Host	2	
47	SDA	2-wire Serial interface data	LVC MOS- I/O	Bi-directional	3	Open-Drain with pull up resistor on Host
48	GND	Ground			1	
49	TX7n	Transmitter Data Inverted	CML-I	Input from Host	3	

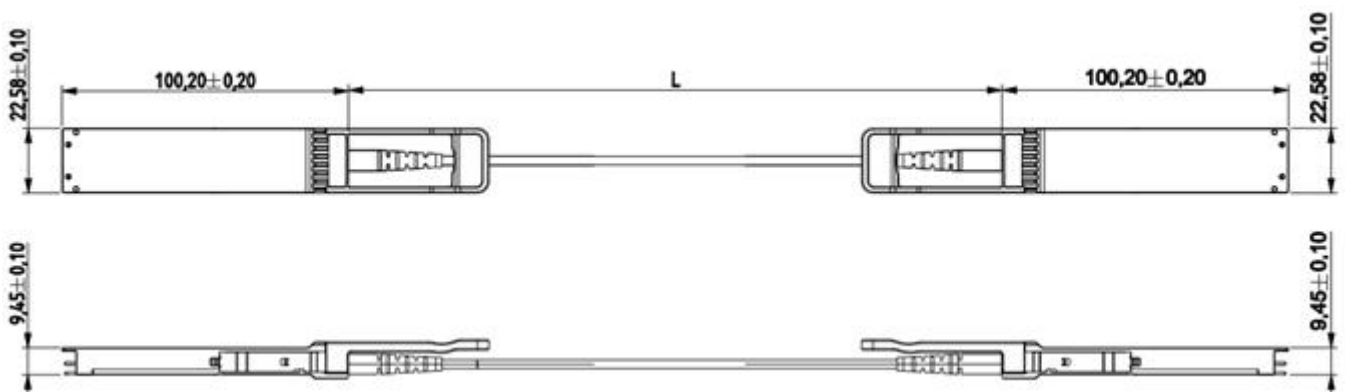
50	TX7p	Transmitter Data Non-Inverted	CML-I	Input from Host	3	
51	GND	Ground			1	
52	TX5n	Underfined	CML-I	Input from Host	3	
53	TX5p	Underfined	CML-I	Input from Host	3	
54	GND	Ground			1	
55	TX3n	Transmitter Data Inverted	CML-I	Input from Host	3	
56	TX3p	Transmitter Data Non-Inverted	CML-I	Input from Host	3	
57	GND	Ground			1	
58	TX1n	Transmitter Data Inverted	CML-I	Input from Host	3	
59	TX1p	Transmitter Data Non-Inverted	CML-I	Input from Host	3	
60	GND	Ground			1	

Electrical Power Supply Characteristics

Parameter	Symbol	Min	Typ.	Max	Units
Power Supply Voltage	VCC1 , VCCTx, VCCR _x	3.13	3.30	3.47	V
Power Consumption	PW	-	-	10	W
Power Consumption-LP mode	-	-	-	1.5	W

Notes: The specified characteristics are met within the recommended range of operation. Unless otherwise noted typical data are quoted at nominal voltage and +25°C ambient temperature.

Package Outline



AOC product bagging circle size:

L	Disc fiber diameter (mm)	number of circle
0.5m	Based on actual circling	1.5
1m		3.5
1.5m	90 ≤ Inner diameter, outer diameter ≤ 110	4.5
2m	100 ≤ Inner diameter, outer diameter ≤ 120	5.5
2.5m	110 ≤ Inner diameter, outer diameter ≤ 130	6.5
3m	100 ≤ Inner diameter, outer diameter ≤ 120	8.5
3m < L ≤ 5m	110 ≤ Inner diameter, outer diameter ≤ 160	Not required
5m < L ≤ 7m	110 ≤ Inner diameter, outer diameter ≤ 170	
7m < L ≤ 30m	110 ≤ Inner diameter, outer diameter ≤ 180	
30m < L ≤ 50m	110 ≤ Inner diameter, outer diameter ≤ 210	
50m < L ≤ 100m	110 ≤ Inner diameter, outer diameter ≤ 250	

Length tolerance table:

L	Tolerance (mm)
$L \leq 1\text{ M}$	+70/-0
$1\text{ M} < L < 7\text{ M}$	+100/-0
$L \geq 7\text{ M}$	+2%L/-0

Dimensions are in millimeters. All dimensions are $\pm 0.2\text{mm}$ unless otherwise specified. (Unit: mm)

Regulatory Compliance

Feature	Test	Method
Electrostatic Discharge (ESD) to the Electrical Pins	MIL-STD-883E Method 3015.7	Class 1(>1000V for SFI pins, >2000V for other pins.)
Electrostatic Discharge (ESD) Immunity	IEC61000-4-2	Class 2(>4.0kV)
Electromagnetic Interference (EMI)	CISPR22 ITE Class B FCC Class B CENELEC EN55022 VCCI Class 1	Comply with standard
Immunity	IEC61000-4-3	Comply with standard
Eye Safety	FDA 21CFR 1040.10 and 1040.11 EN (IEC) 60825-1,2	Compatible with Class I laser Product

Ordering Information

Part. No	Specifications								
	Pack	Rate (Gbps)	Tx (nm)	Po (dBm)	RX	Sen (dBm)	Temp (°C)	Reach (M)	DDM
AC-OPRAOC-8G800-xx	OSFP-RHS	800G	VCSEL 850	-4.6~4	PIN	<-6.4	0~70	100	Y